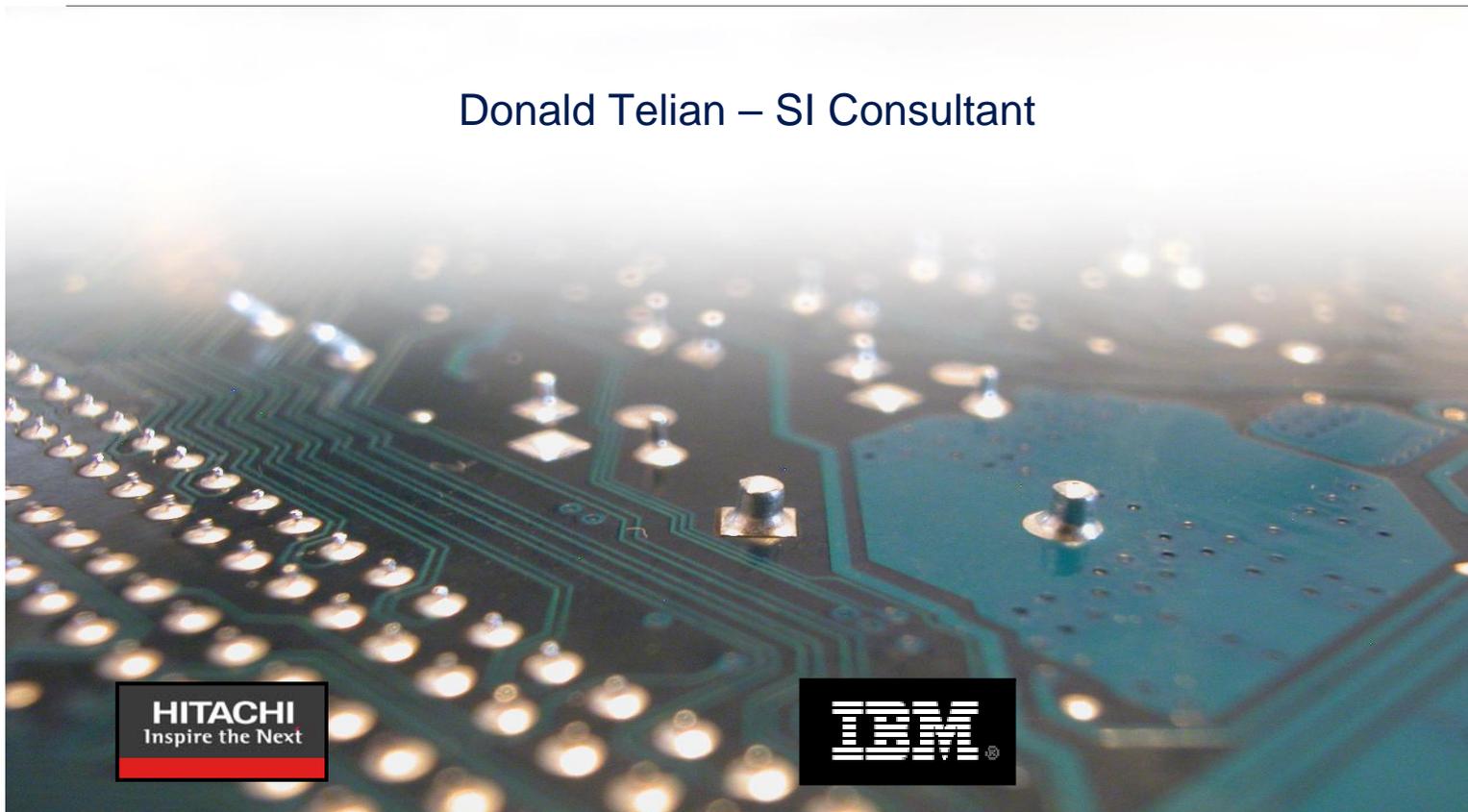
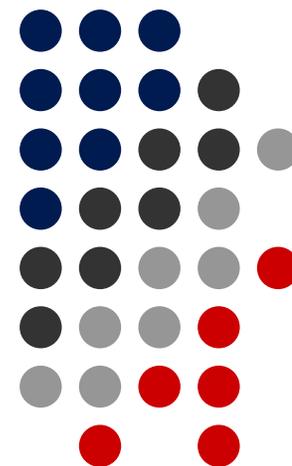


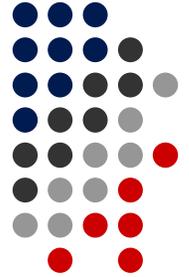
# New Technologies for 6 Gbps Serial Link Design & Simulation, a Case Study

Session 8ICP8

Donald Telian – SI Consultant



# About the Authors



**Donald Telian** is an independent Signal Integrity Consultant. Building on over 23 years of SI experience at Intel, Cadence, HP, and others, his recent focus has been on helping customers correctly implement today's Multi-GHz serial links. He has published numerous works on this and other topics. Donald is widely known as the SI designer of the PCI bus and the originator of IBIS modeling and has taught SI techniques to thousands of engineers in more than 15 countries. Donald can be reached at: [telian@sti.net](mailto:telian@sti.net)

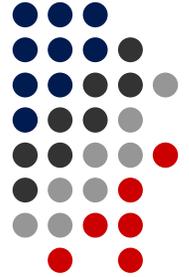
**Paul Larson** is a senior Hard Disk Drive (HDD) development engineer for Hitachi GST. Prior to that he held a similar position at IBM, for a combined 29 years of experience in HDD development, integration and in ensuring FC and SAS HDD Signal Integrity. Paul can be reached at: [paul.larson@hitachigst.com](mailto:paul.larson@hitachigst.com)

**Ravinder Ajmani** is a Senior Engineer with Hitachi GST. He has over 15 years of experience on High-speed PCB Design, Signal integrity, and Electromagnetic Compatibility. During this period he has worked on several generations of disk drive products, and resolved numerous design and customer integration issues with these products. Ravinder can be reached at: [Ravinder.Ajmani@HitachiGST.com](mailto:Ravinder.Ajmani@HitachiGST.com)

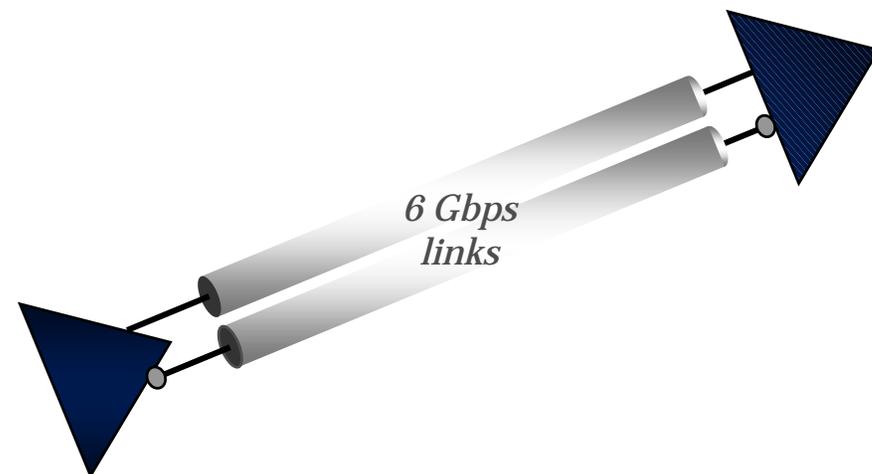
**Kent Dramstad** is an ASIC Application Engineer at IBM. He has over 27 years of experience working on both power and signal integrity issues for a wide variety of applications. His current emphasis is on helping customers select and integrate IBM's series of High Speed Serdes (HSS) cores into their ASIC designs. Kent can be reached at: [dramstad@us.ibm.com](mailto:dramstad@us.ibm.com)

**Adge Hawes** is a Development Architect for IBM at its Hursley Labs, United Kingdom. He has worked for IBM for more than 30 years across such hardware as Graphic Displays, Printing Subsystems, PC development, Data Compression, and High-Speed Serial Links. He has represented the company in many standards bodies such as PCI, SSA and Fibre Channel. Recently he has moved from Digital Logic to Analog and Mixed-Signal, where he develops simulators for IBM's High Speed Serial Link customers. Adge can be reached at: [adge@uk.ibm.com](mailto:adge@uk.ibm.com)

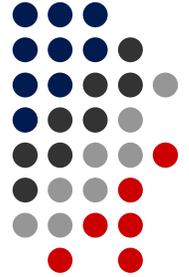
# Agenda



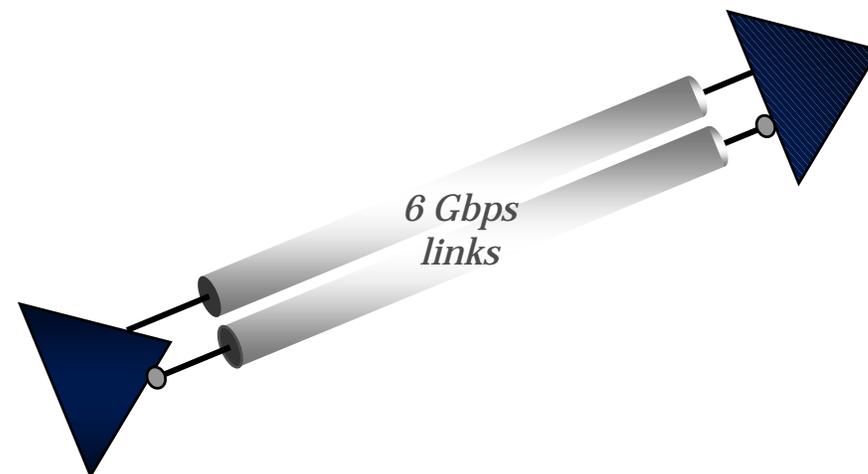
- Intro to Project, Tools, & Technologies
- Verifying SAS Spec Compliance
- Virtual Systems Analysis
- Conclusions



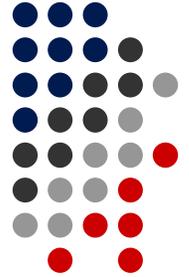
# Agenda



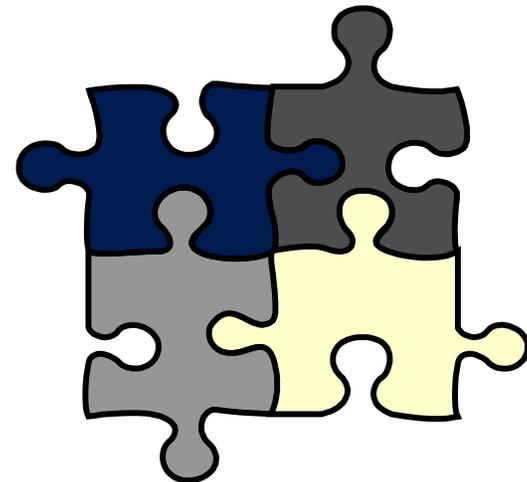
- ▶ ● Intro to Project, Tools, & Technologies
- Verifying SAS Spec Compliance
- Virtual Systems Analysis
- Conclusions



# About the Project

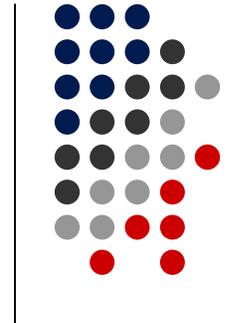


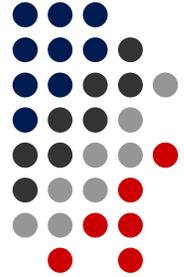
- Identify and implement new simulation environment for future 6+ Gbps Hard Disk Drive (HDD) designs
- Prove-in environment on design of future products
- 6 Gbps Challenges
  - Loss ~20dB (10% of Tx signal at Rx)
  - Rx signal un-measurable
  - Complex equalization schemes
  - New model formats (AMI)
  - New simulation techniques
  - New modeling standards emerging
  - Spec compliance requires simulation
- Coordinate ~15 key industry players
  - Customers, suppliers, tool vendors, standards committees



# Project Phases

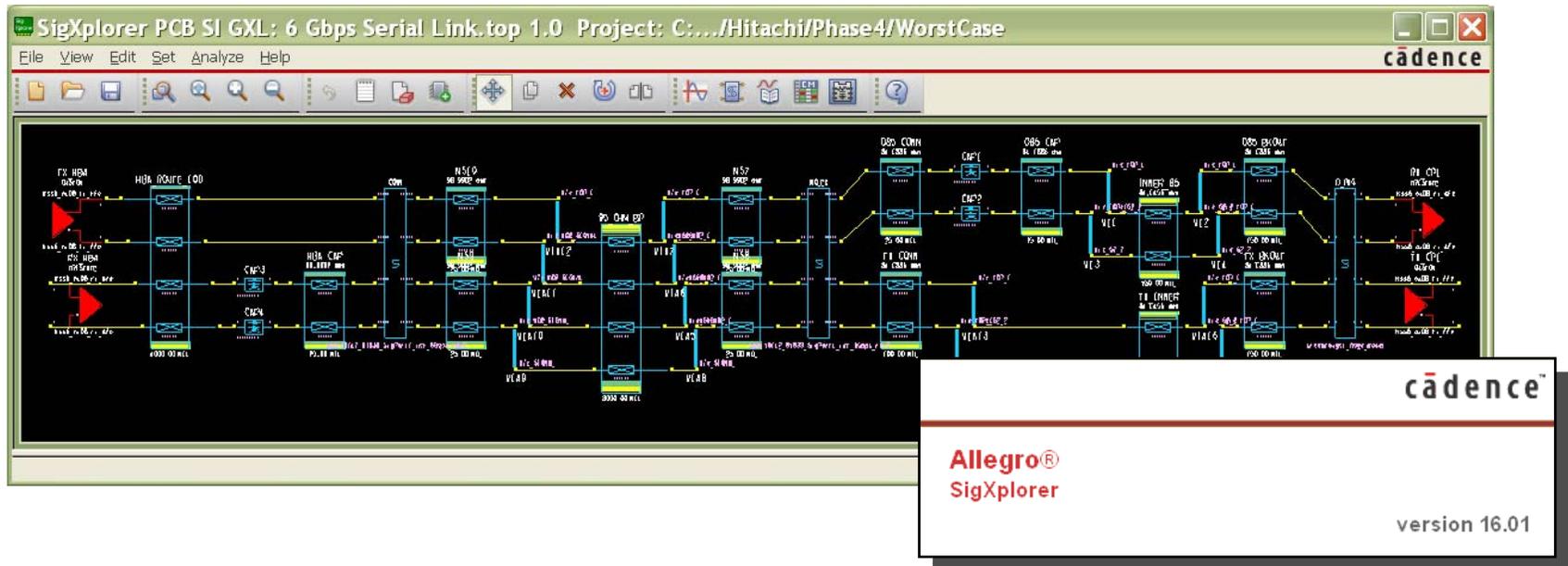
- Assessment
- Proof-of-Concept
- Model Development
- System Analysis
- Kit Environment
  
- ~ 6-month Effort



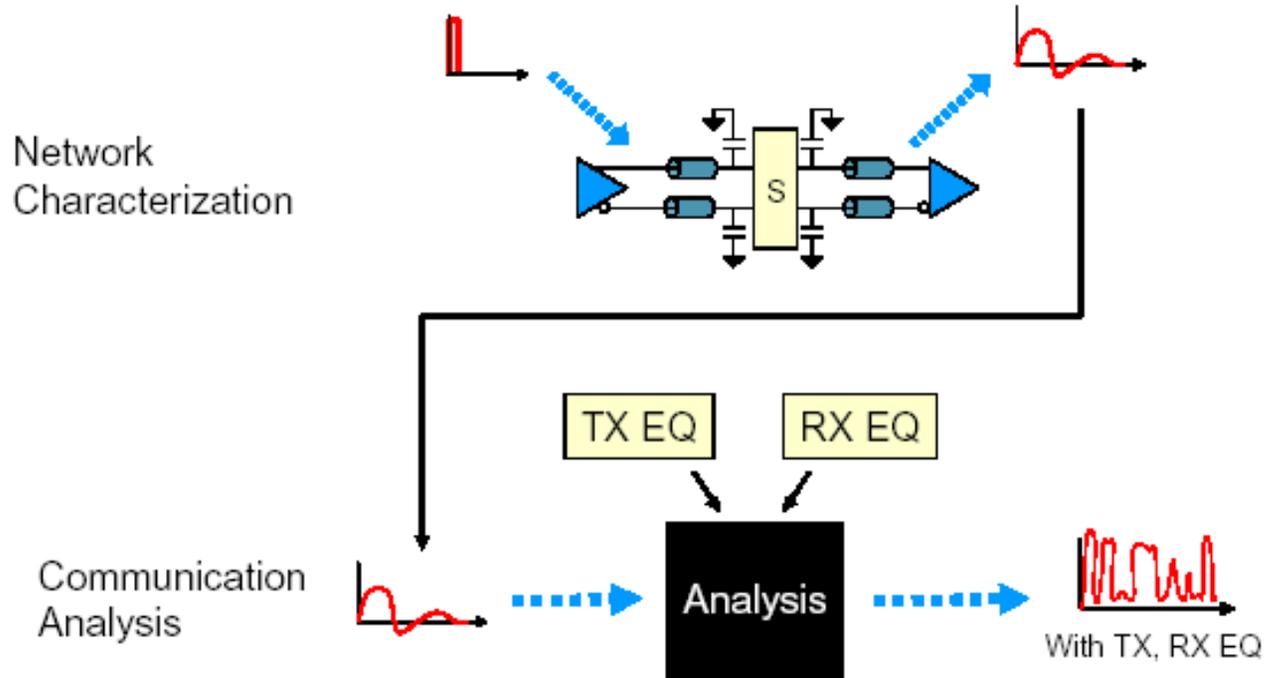
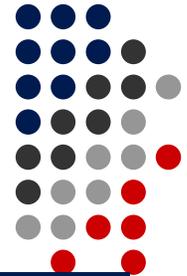


# Tools, Models

- Cadence Allegro PCB SI GXL SigXplorer 16.01
  - Channel Analysis, S-Parameters, Via Modeling
  - SigWave, MacroModels, PCB Field Solvers, Tlsim
- IBM HSS 6 Gbps SerDes AMI Model Kit



# AMI Model Review

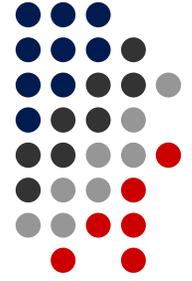


Circuit Analysis  
with  
Existing Models

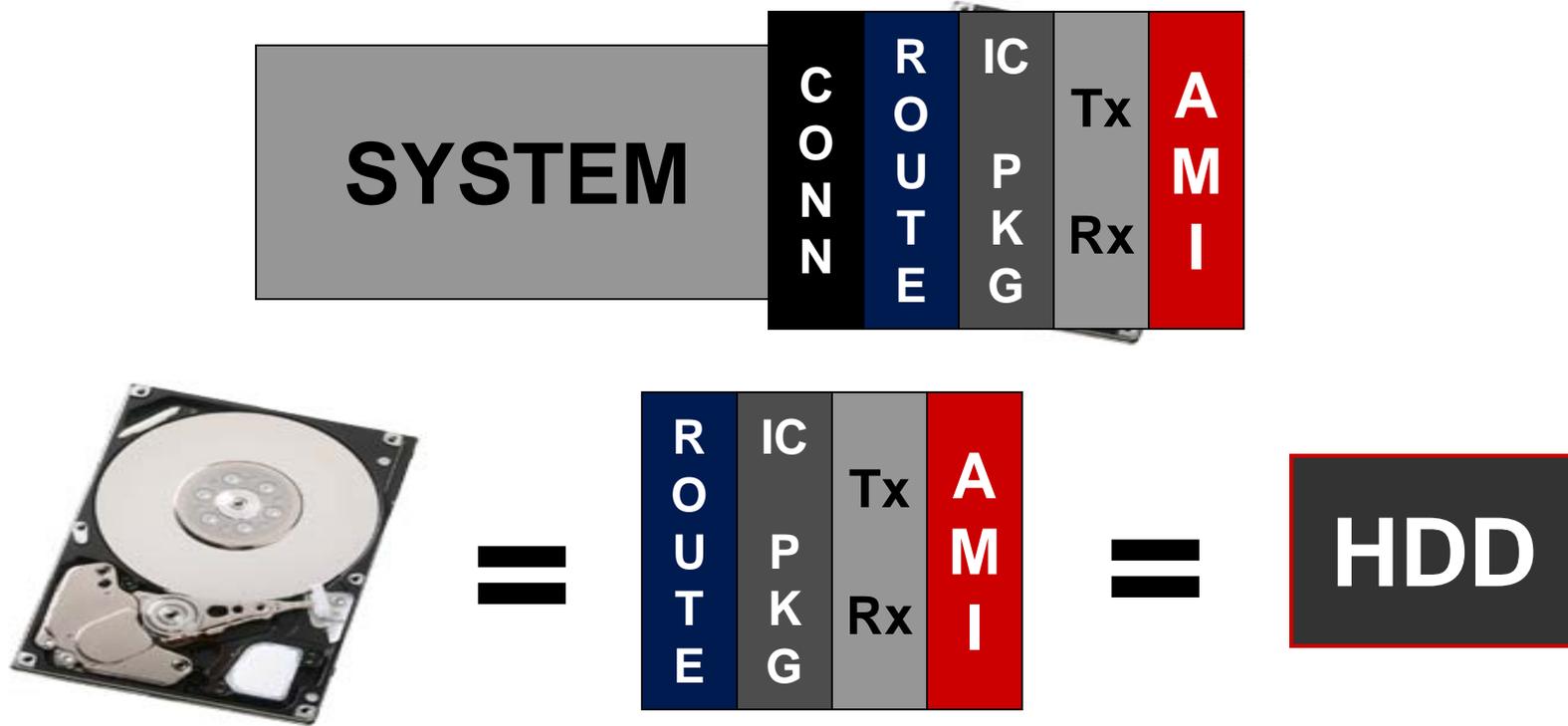
Algorithmic  
Models

Image courtesy IBIS-ATM Group and Todd Westerhoff: <http://www.vhdl.org/pub/ibis/summits/sep07/>

- Algorithmic models typically implemented in .dll files
- AMI format approved by IBIS Committee in Nov. '07
- More background see: [CDNLive! 2007 Session 8.3](#)

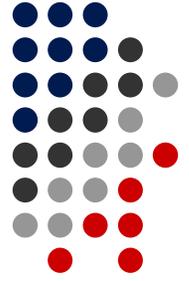


# Hard Disk Drive Model

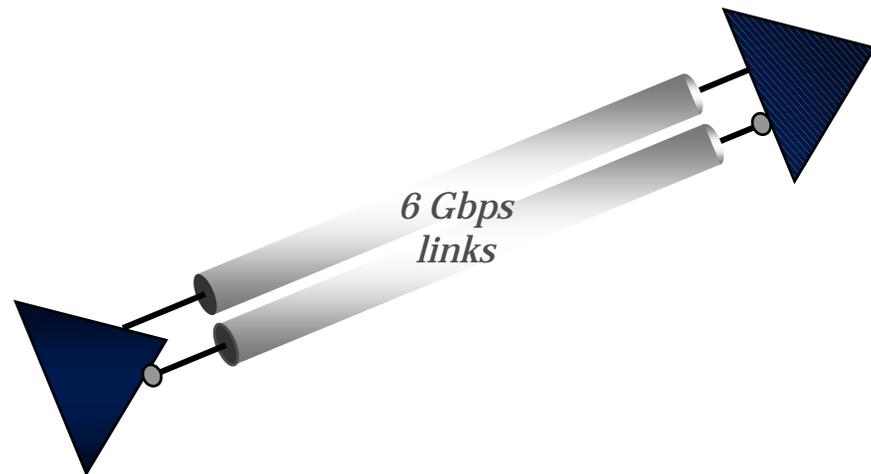


*HDD model used with both compliance and system loads*

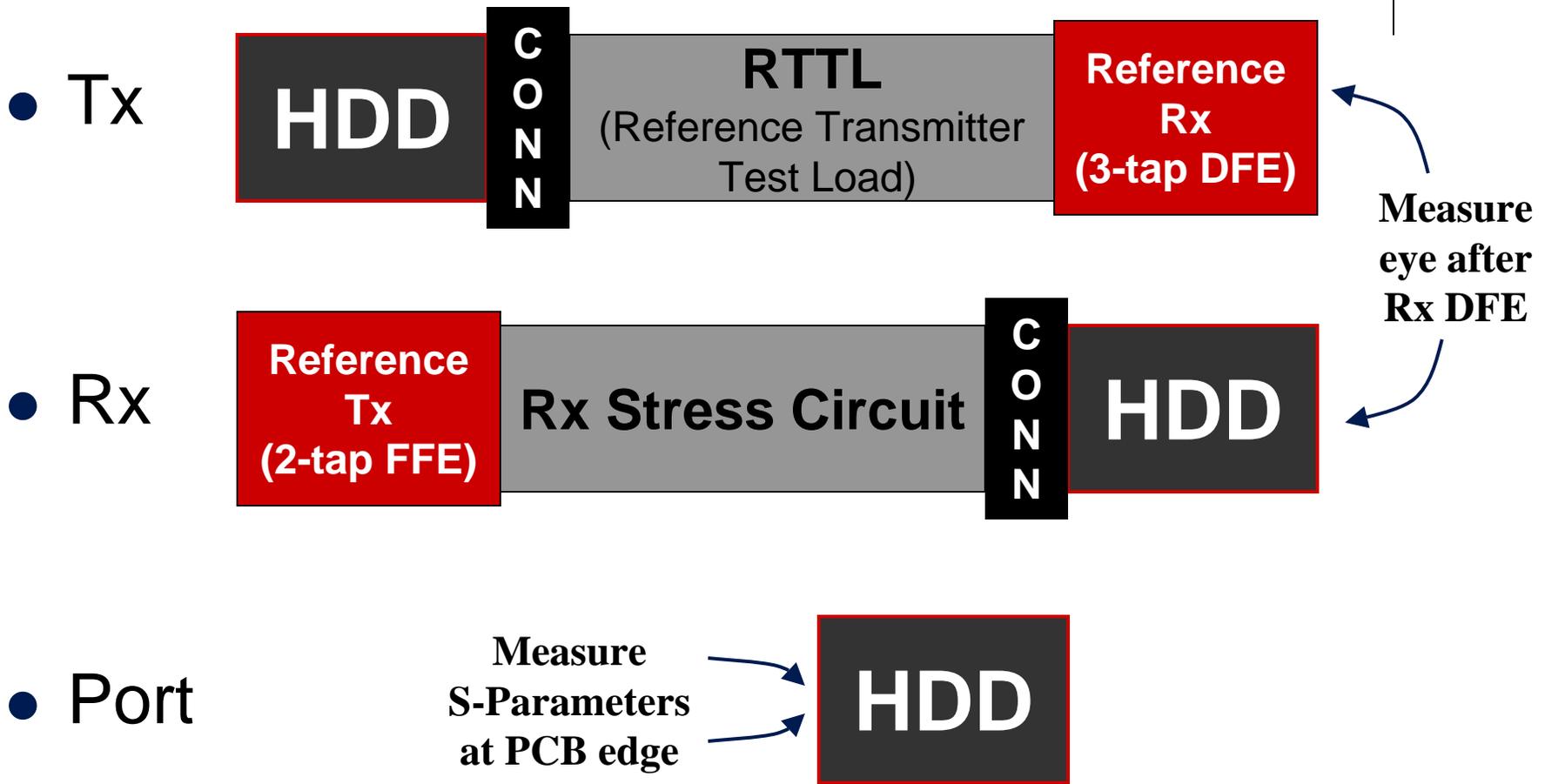
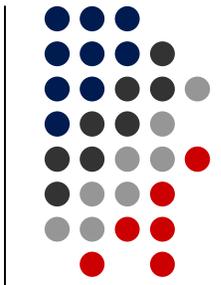
# Agenda

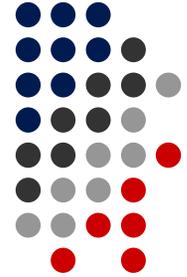


- Intro to Project, Tools, & Technologies
- ▶ ● Verifying SAS Spec Compliance
- Virtual Systems Analysis
- Conclusions



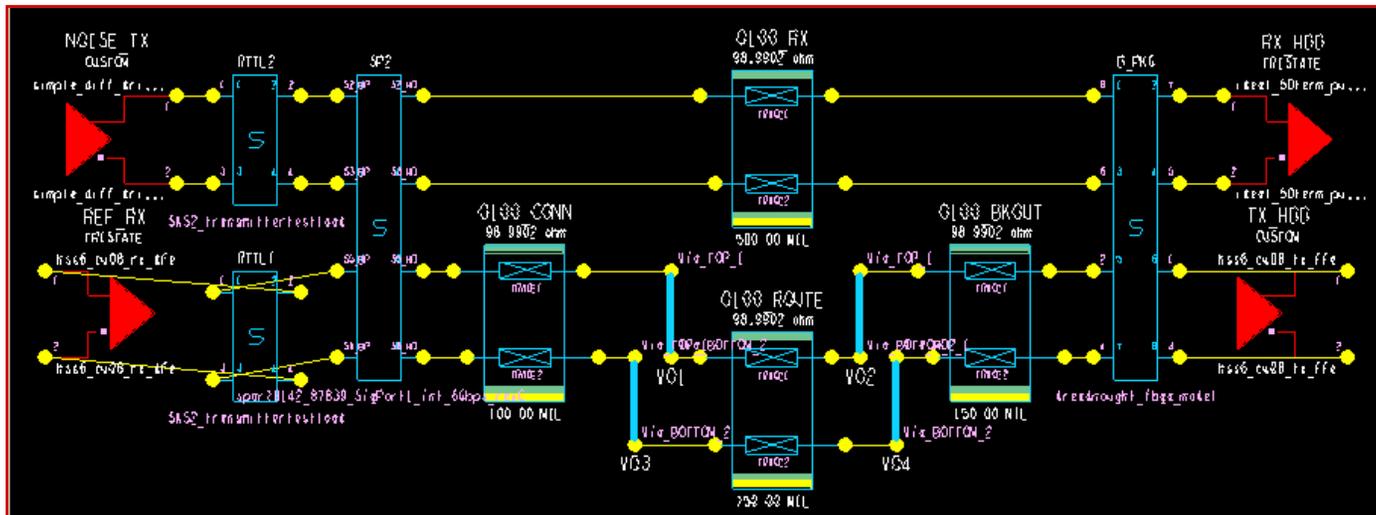
# SAS Compliance Testing





# Tx Compliance Testing

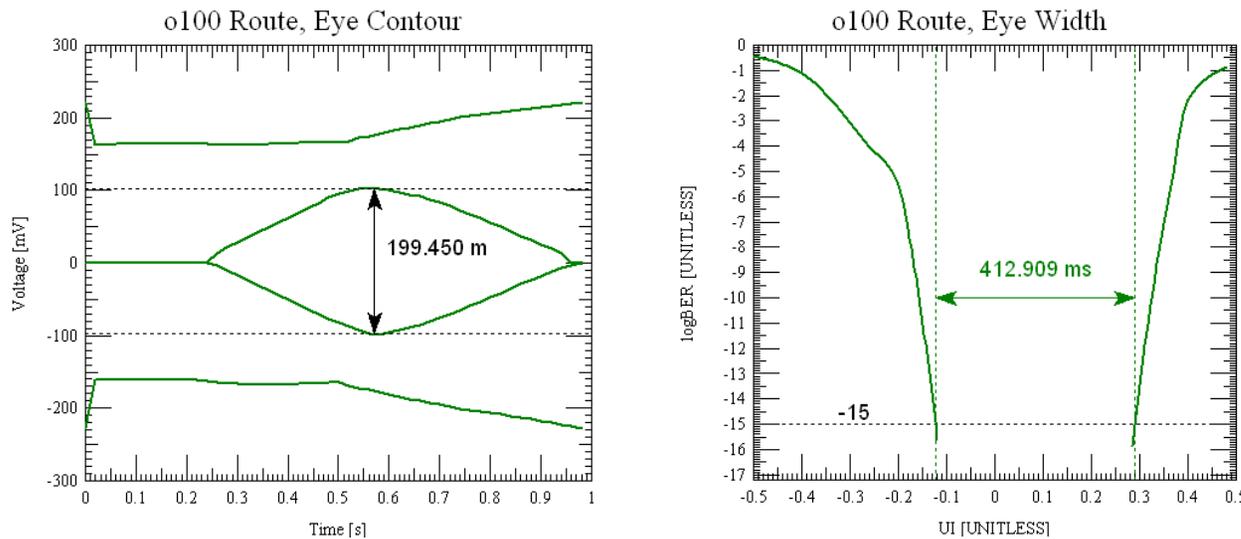
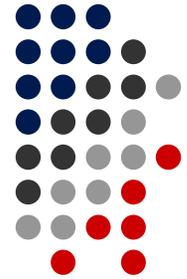
- Simulation specified as only way to validate
  - Eye measured inside IC at output of Rx DFE
  - Spec calls out Reference Rx 3-tap LMS DFE
- Transmit through -15dB “RTTL” S-parameters



Noise Channel

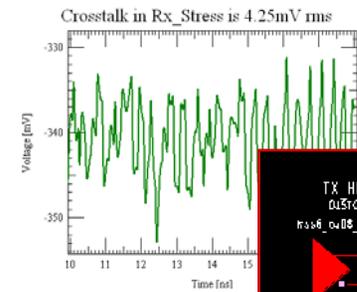
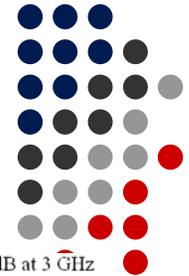
Channel Under Test

# Tx RTTL Simulation Results



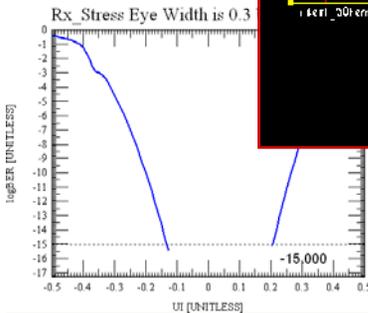
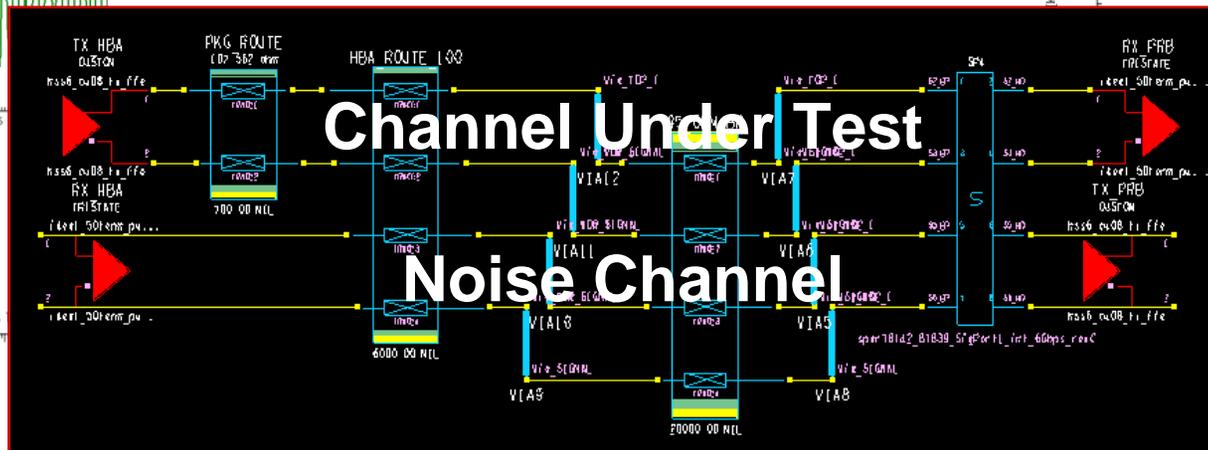
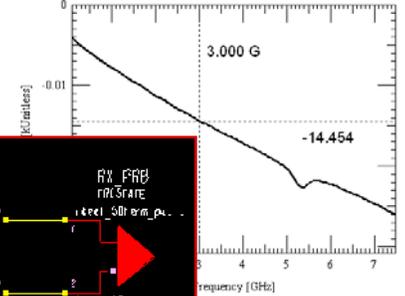
- 4 taps configured in Tx, noise channel active
- Height/width = 179mV/0.41UI (100/0.40 spec)
- Comfortable with small margin on width
- Tool issues noted in paper

# Rx Compliance Testing

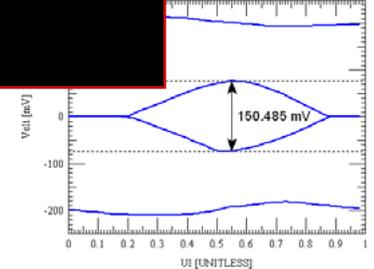


SAS device connects here

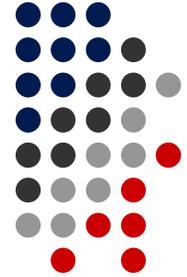
Rx Stress Loss, SDD21 is -14.5 dB at 3 GHz



Height is 150 mV at IR/CR

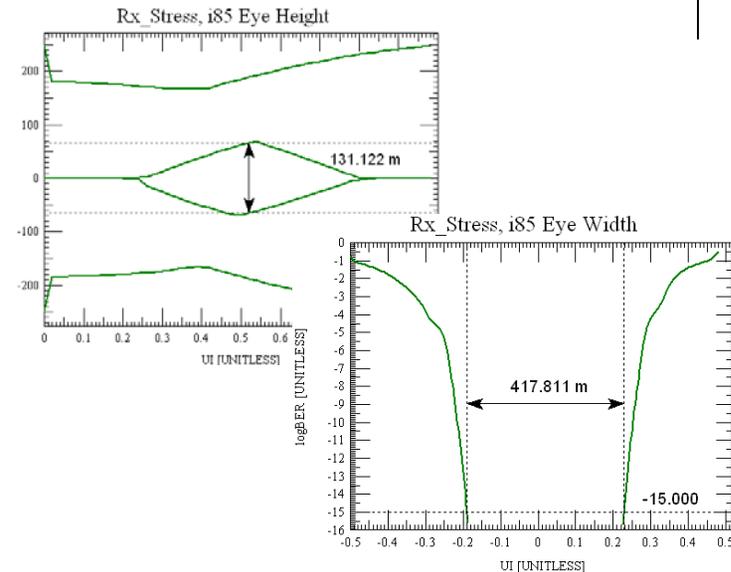


- Rx stress testbench implemented in *simulation* environment
- Delivered crosstalk, loss, eye w/h, from Reference Tx as specified



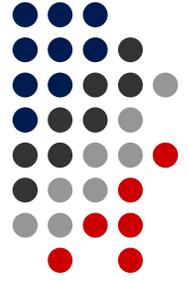
# Rx Stress Test Results

- Two HDD route styles tested
  - 100 Ohm microstrip
  - 85 Ohm stripline
- Eye height & width measured at 1e15 bits
  - height extrapolated
- Derive design margins
- Guide design choices

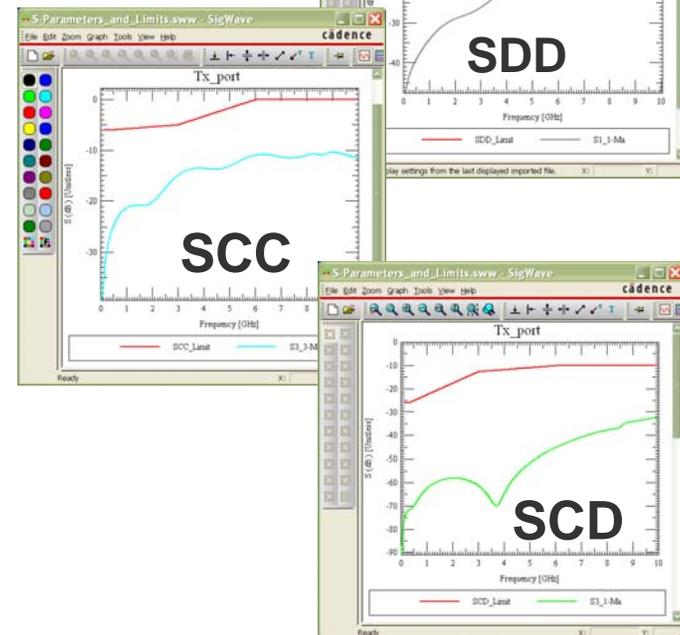
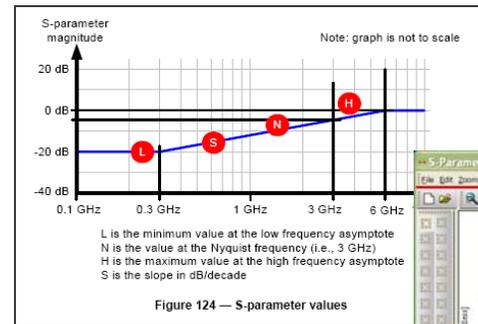


Parameter	o100	i85	Unit
Eye Height (1e6 bits)	108	131	mV
Eye Height Margin (60mV - 10%)	<b>37</b>	<b>58</b>	mV
Eye Width (1e15 bits)	0.408	0.418	UI
Margin in UI (target = 0.2 UI min)	0.208	0.218	UI
Margin in pS	<b>35</b>	<b>36</b>	pS

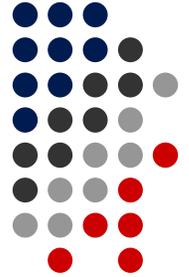
# S-Parameter Limit Compliance



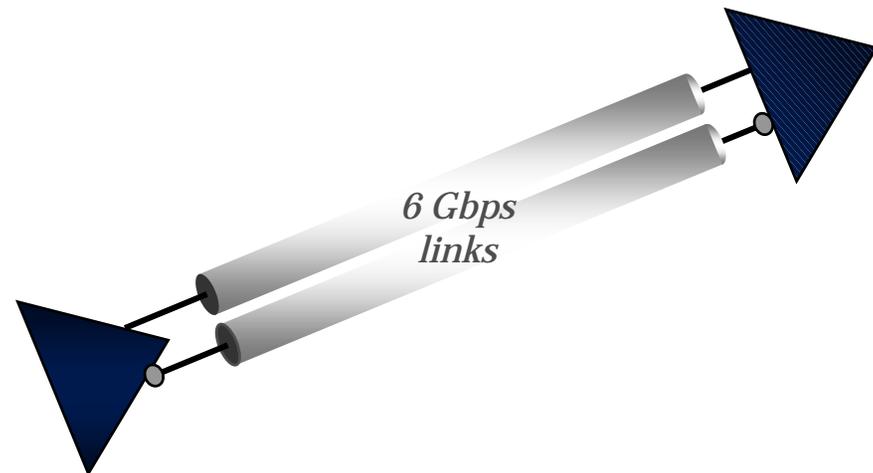
- Differential nets extracted for virtual VNA measurement
- Plot SDD, SCC, SCD against specified limits (in red)
- Procedure detailed in paper



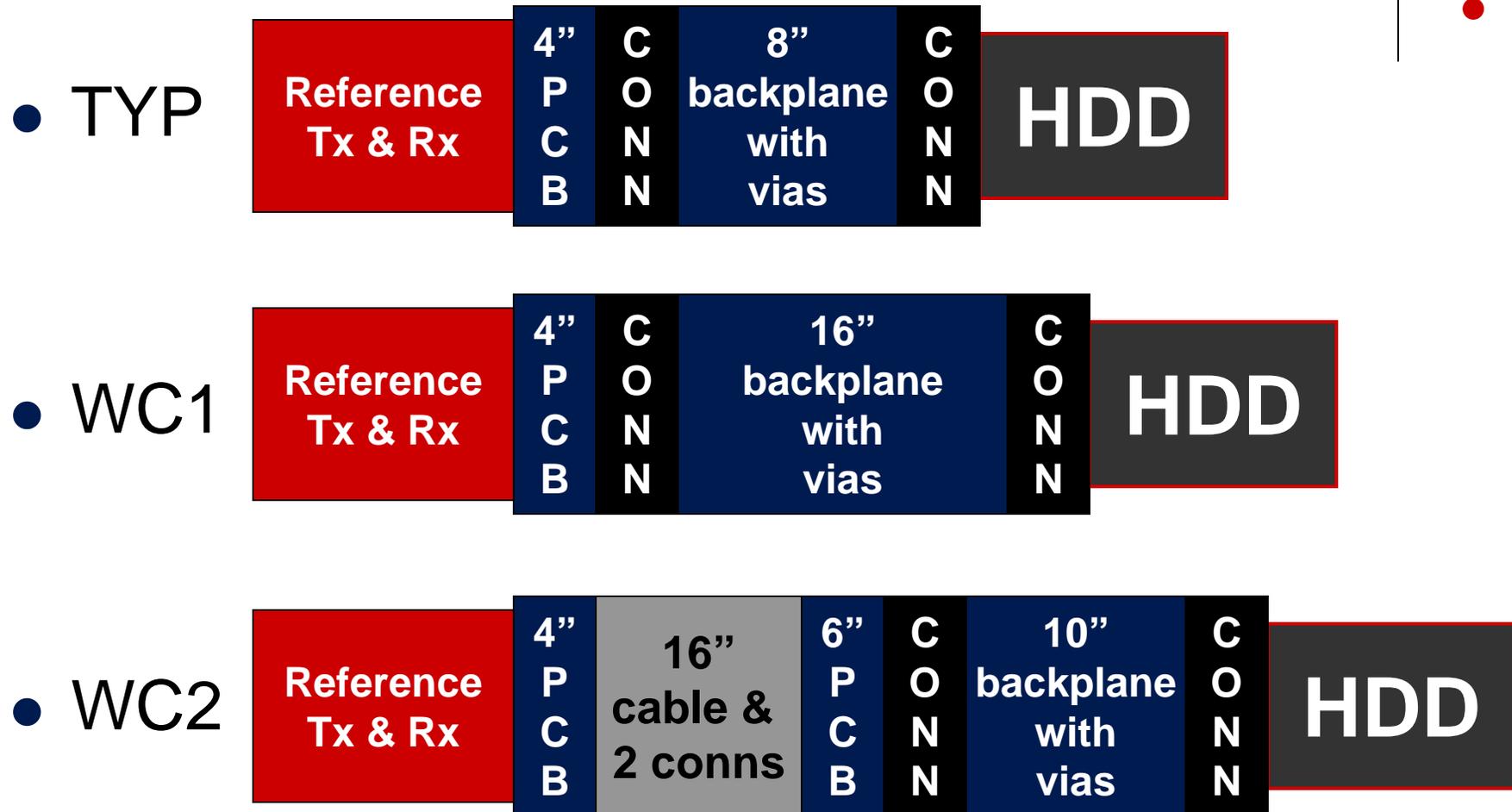
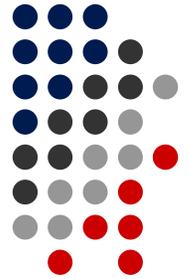
# Agenda



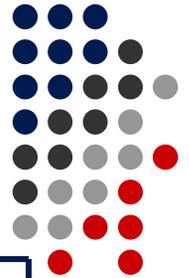
- Intro to Project, Tools, & Technologies
- Verifying SAS Spec Compliance
- ▶ ● Virtual Systems Analysis
- Conclusions



# System Configuration Testing

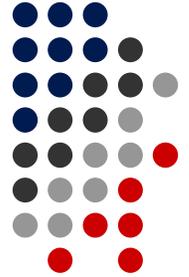


# System Configuration Metrics



Parameter	TYP	WC1	WC2	Unit
PCB & Cable Length	13	21	37	inches
# of Connectors	2	2	4	#
# of Vias	4	4	4	vias
Propagation Time	2.5	4	6	nS
6 Gbps bits in channel	15	24	36	bits
Channel Loss (SDD21 @ 3 GHz)	-8.9	-13.6	-16	dB

- Apply experience to augment spec's coverage
- Acquire intuitive sense of what works, what doesn't
- Wide range of length, loss, discontinuities
- Drive with minimal Tx, recover signal with IBM DFE



# 7-Step Link Analysis Process

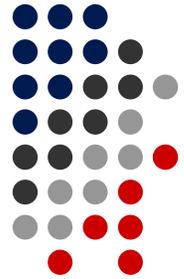
Step	Task	Purpose	Output
1	Collect & Connect Models	Build Link Model	Link Ready-to-Run
2	Model Sanity Check	Verify Model	TD Functional
3	Quantify Loss & Crosstalk	Understand & Gauge Link	S21 dB, mV RMS
4	Plot Impulse Response & ISP	Measure ISP, Calculate #bits	#bits for CA
5	Verify Eye Convergence	Test #bits, Confirm Coverage	CA Functional
6	Parameter Determination	Setup for Worst-Case	CA Parameters
7	Corner Case Analysis	Derive Design Margins	Eye h/w Margins

*Illustrate on WC1 channel (TYP & WC2 in paper)*

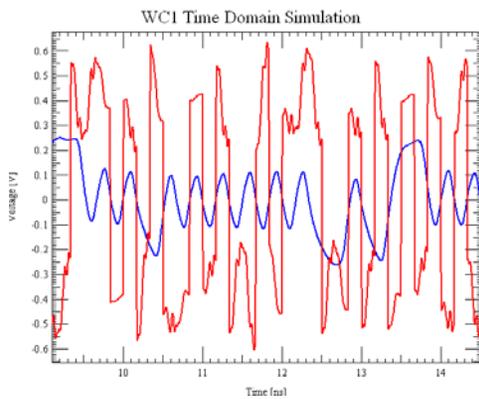
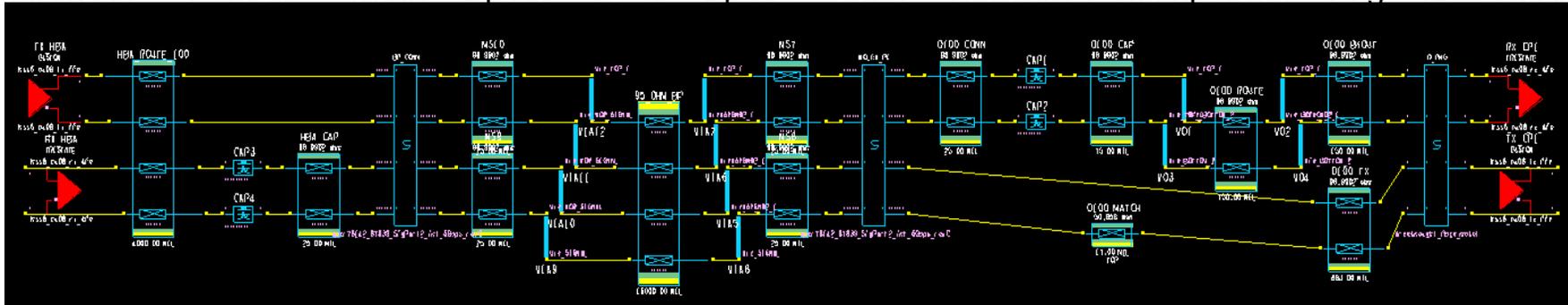
*Can be applied to any serial link SI analysis*

# Step 1: Collect & Connect Models

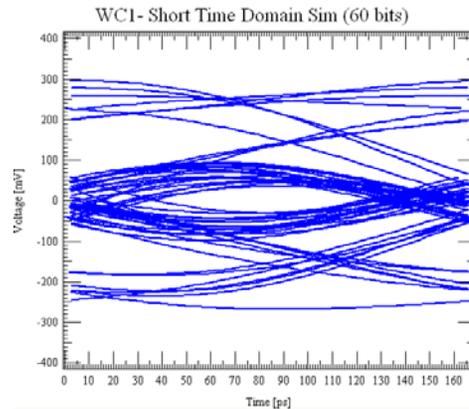
## Step 2: Model Sanity Check



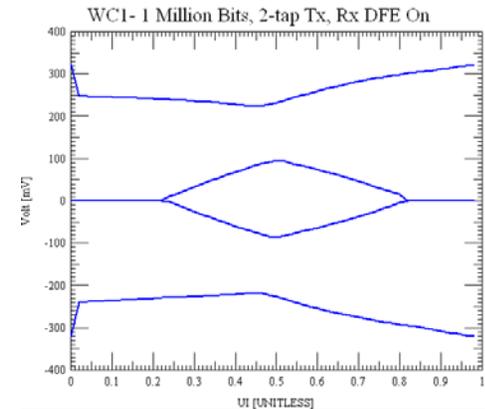
CtrlTx/Rx – 4” trace – Conn – BpVia – 16” tr – BpVia – Conn – 100Ohm 1” mstrip trace – Pkg – IBM Tx/Rx



Voltages, System Loss, Time Delay Reasonable

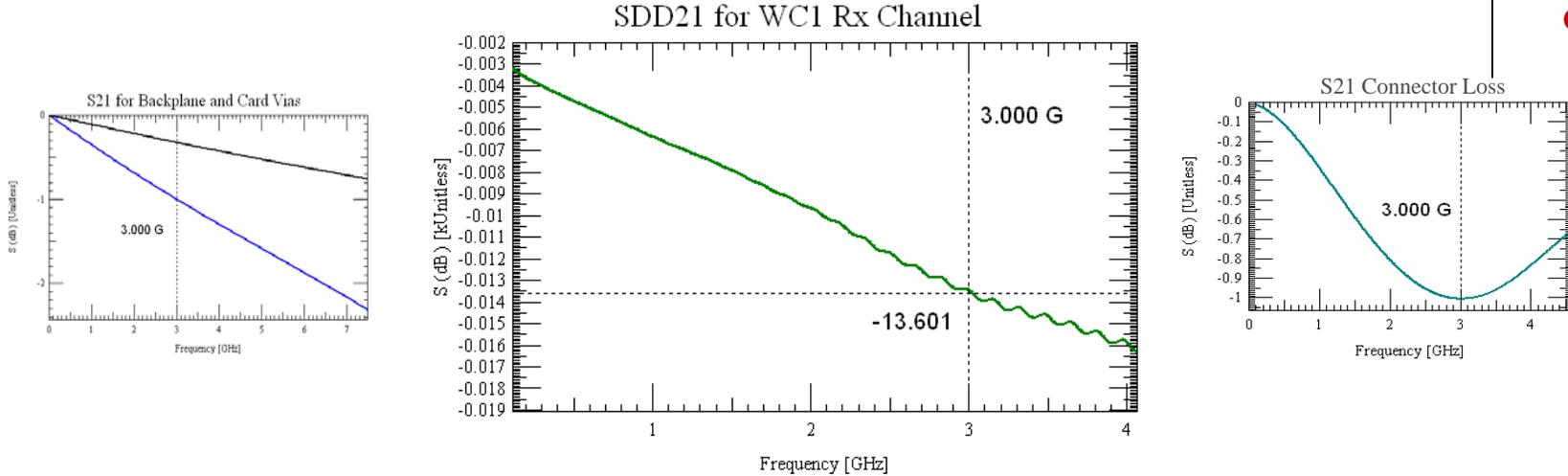
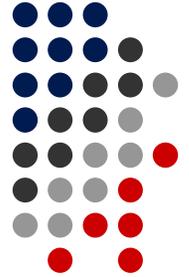


Short TD Eye at Rx Input Mostly Collapsed

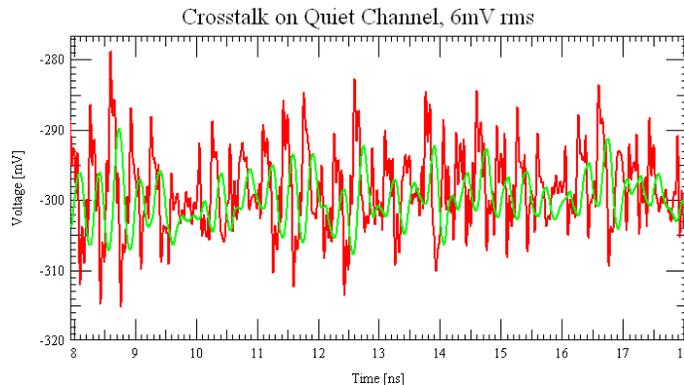


Typical CA Eye Re-opened, Rx DFE Functioning

# Step 3: Quantify Loss & Crosstalk



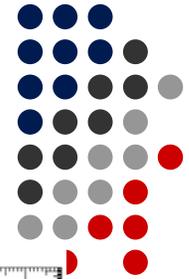
Total Loss = 2\*BpVia + 2\*CdVia + 2\*Conn + 21\*0.33dB/inch + Misc  
 Hand Calculation = 2\*1 + 2\*0.3 + 2\*1 + 21/3 + 2 = 13.6dB



Crosstalk = 5.6 mV rms

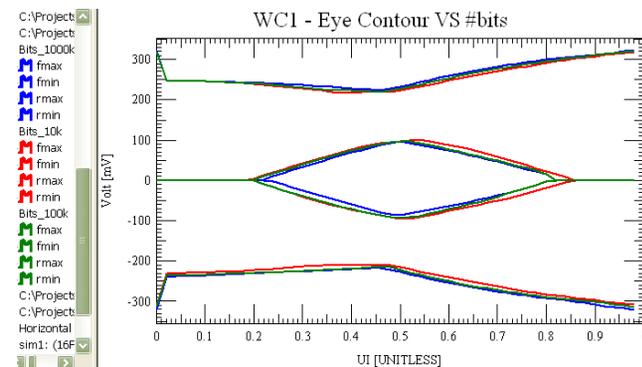
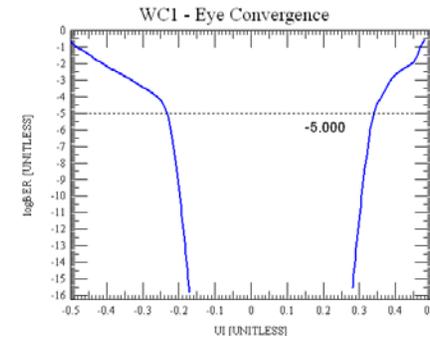
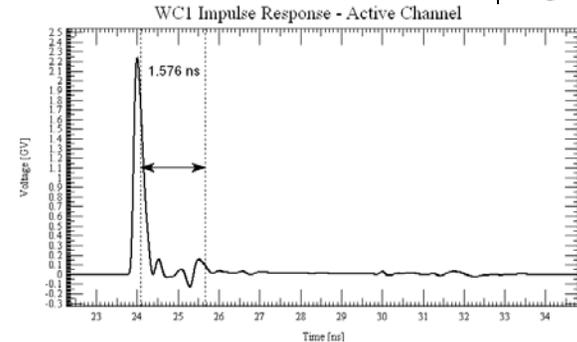
# Step 4: Plot Impulse Response & ISP

## Step 5: Verify Eye Convergence

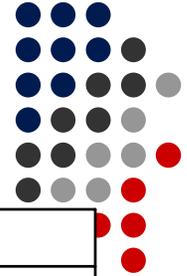


- Impulse Response shows noise to  $\sim 8\text{nS}$
- Interconnect Storage Potential (ISP) =  $1.6\text{ nS}$
- Bit affected by 10 bits previous (1 symbol)
- Eye converges  $\sim 1\text{e}5$  bits
- #bits parameter for CA
- ISP defined in [this paper](http://www.cdnusers.org/community/allegro/Resources/resources_pcbst/mgh/TP_Dcon05_ISP_CA_Intel.zip)

[http://www.cdnusers.org/community/allegro/Resources/resources\\_pcbst/mgh/TP\\_Dcon05\\_ISP\\_CA\\_Intel.zip](http://www.cdnusers.org/community/allegro/Resources/resources_pcbst/mgh/TP_Dcon05_ISP_CA_Intel.zip)

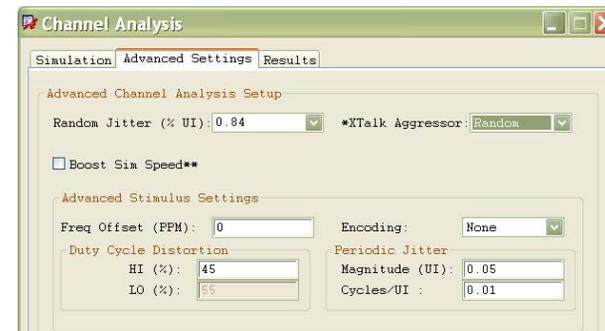


# Step 6: Parameter Determination

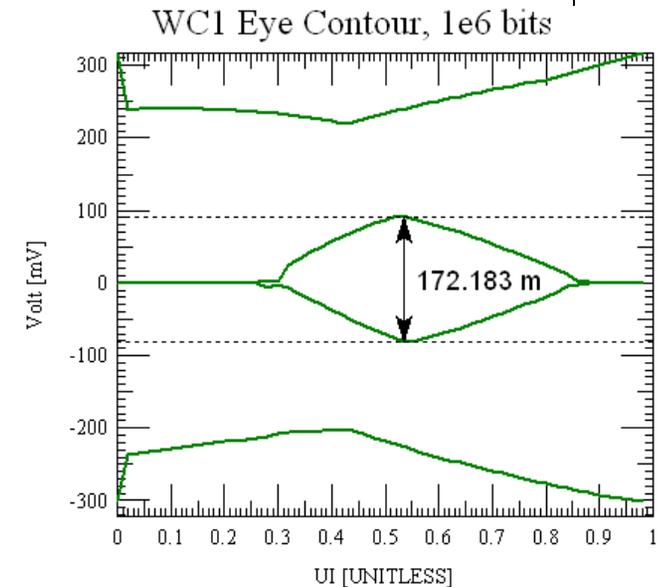
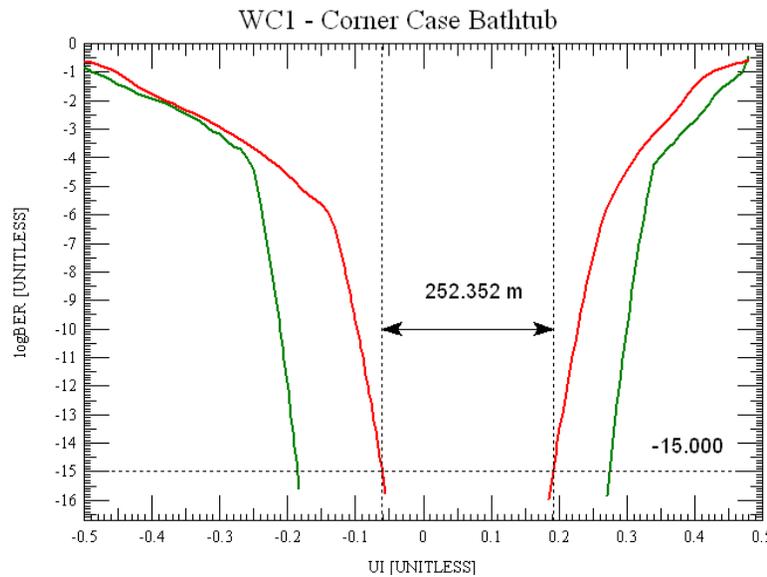
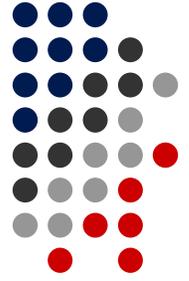


#	Variable	Influences	Source	Value	Unit	Apply In	Notes
1	Tx Swing	Eye shape	SAS Spec Table 61	800	mV ppd	Tx Model	minimum allowed
2	Tx De-emp	Eye shape	SAS Tables 64 65	-2	dB	Tx Model	Ref Tx value
3	Bit Pattern	Jitter, Eye	SAS Spec, etc	CJTPAT		CA Form	
4	Dj	Eye, B-tub	Tx Parameter	23.4	pS p-p	chsim.cim	= 0.14% UI
5	Rotator Linearity	Eye, Bathtub	AMI Model Kit	pr_slow.dat	file	Rx model	pr_fast.dat a bit better
6	On-chip Sparams	Eye shape	AMI Model Kit	0		Tx/Rx models	enabled
7	Rj	Eye, B-tub	Tx Parameter	1.4	pS rms	CA Form	= 0.84% UI
8	Duty Cycle Dist.	Eye shape	Tx Parameter	0.05	UI	CA Form	Use 45 as HI%
9	Pj Magnitude	Jitter, Eye	AMI Model Kit	0.05	UI	CA Form	Enter as 0.05
10	Pj Cycles/UI	Jitter, Eye	AMI Model Kit	0.01	UI	CA Form	Enter as 0.01

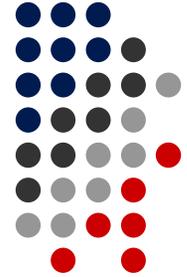
- Extract from specs
- Needed for worst-case
  - Unlike standard SI
- GUI = all but Tx Dj



# Step 7: Corner Case Analysis

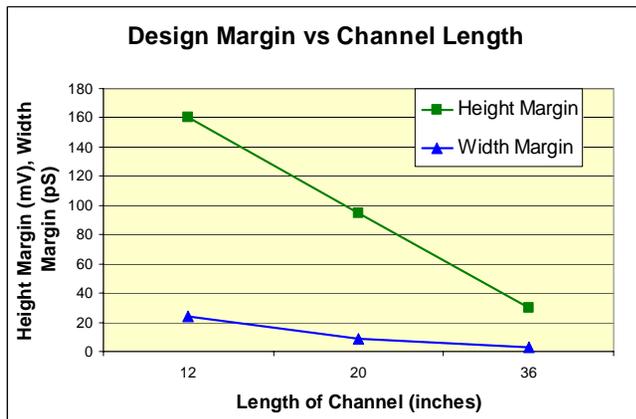


- Width: corner (red) decreases significantly to 0.25 UI
- Height: must derate to 1e15 (155 mV)
- Margin: 95mV/0.05UI against 60mV/0.20UI targets



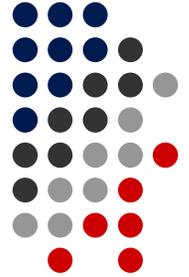
# Margins for All Systems

- Margins at 1e15 per SAS spec
- IBM Rx DFE Handles all Cases
- WC2 Margins Approaching Limit

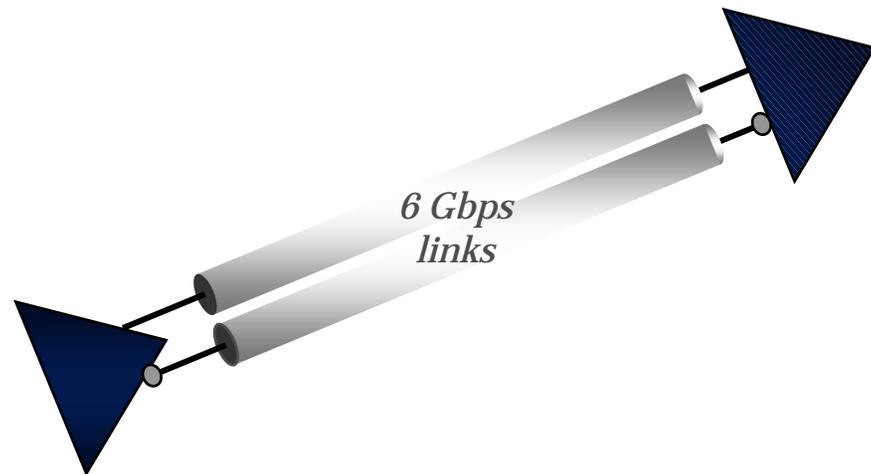


Parameter	TYP	WC1	WC2	Unit
PCB & Cable Length	13	21	37	inches
# of Connectors	2	2	4	#
# of Vias	4	4	4	vias
Propagation Time	2.5	4	6	nS
6 Gbps bits in channel	15	24	36	bits
Channel Loss (SDD21 @ 3 GHz)	-8.9	-13.6	-16	dB
Crosstalk	9.1	5.6	7.4	mV rms
ISP	1.5	1.6	2.1	nS
#bits for Coverage	1e4	1e5	1e5	bits
Corner Eye Height (1e6 bits)	244	172	103	mV
Eye Height Margin (60 mV -10%)	<b>160</b>	<b>95</b>	<b>30</b>	mV
Typ Eye Width (1e6 bits)	0.72	0.59	0.52	UI
Corner Case Width (1e15 bits)	0.34	0.25	0.218	UI
Margin in UI (to 0.20UI target)	<b>0.14</b>	<b>0.05</b>	<b>0.018</b>	UI
Margin in pS	24	9	<b>3</b>	pS

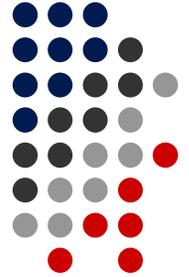
# Agenda



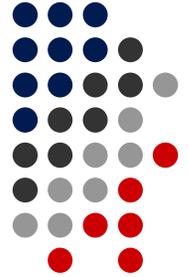
- Intro to Project, Tools, & Technologies
- Verifying SAS Spec Compliance
- Virtual Systems Analysis
- ● Conclusions



# Key Learnings



- HDD implementation has margin against all tests, IBM SerDes performing well
- Worst-case margins become questionable around -16dB, typical channels  $\leq$  -10dB
- 6 Gbps sim environment with AMI models now functional, performance meets expectations
- Environment enables compliance testing that previously required physical hardware

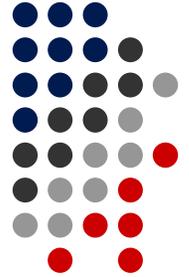


# Tool Improvements Desired

- Add Tx Dj to GUI
- Add bathtub curve for eye height too
- Add CA characterization stop time to GUI
- Calculate RMS voltage from waveforms
- Fix a few minor bugs
- Correlation



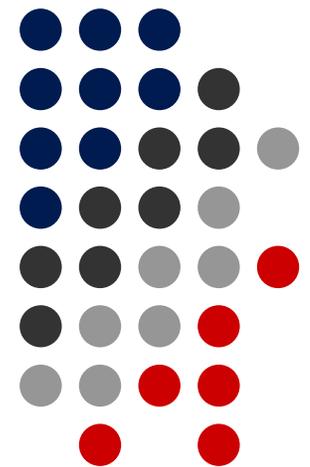
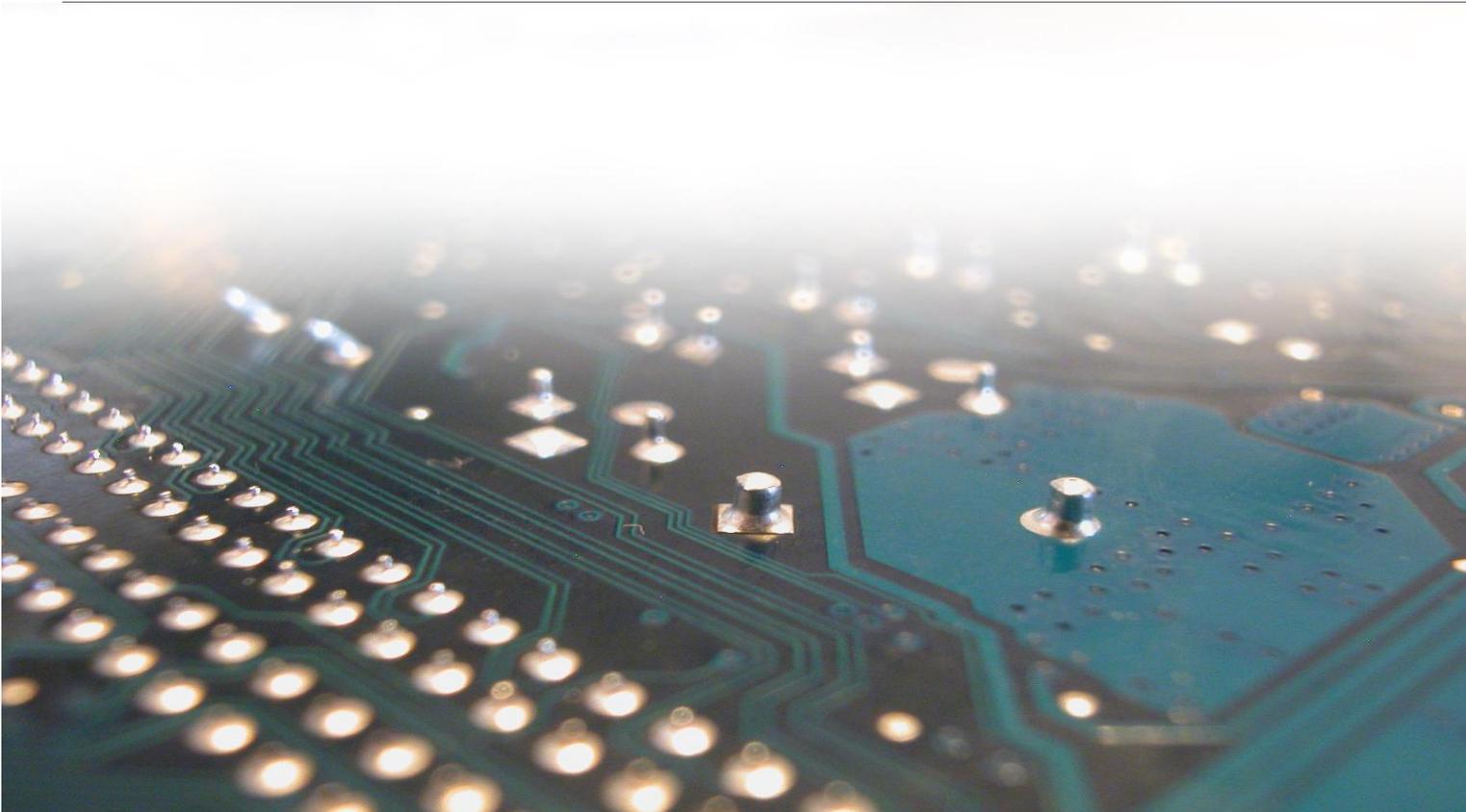
# In Summary



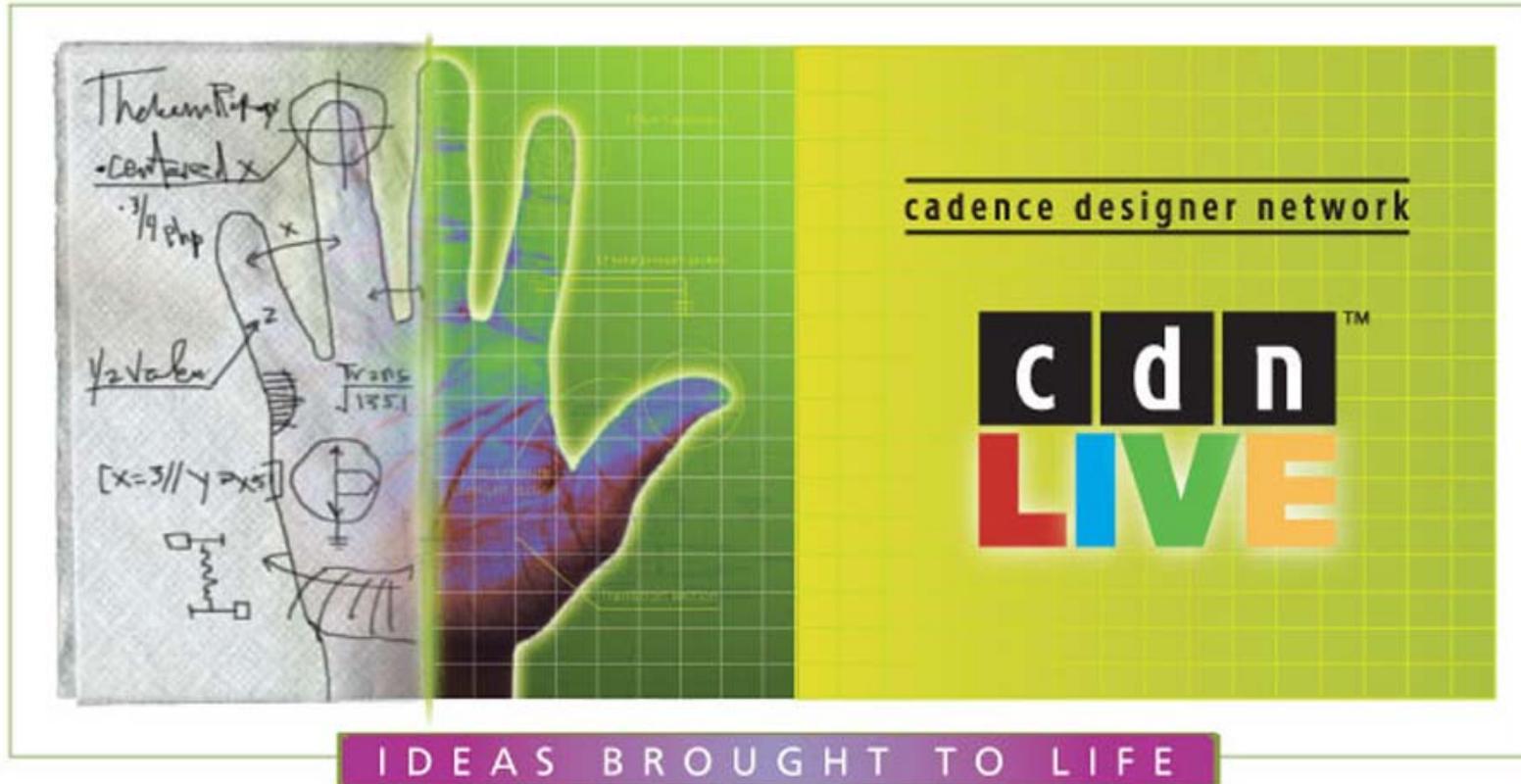
- Serial link frequencies continue to increase
- Specs require virtual probing inside IC
- AMI models are starting to appear
- Simulation environment functional
- A process for link SI described
- Refer to paper for complete details



# THANK YOU



Donald Telian  
SI Consultant  
[telian@sti.net](mailto:telian@sti.net)



© 2008 Cadence Design Systems, Inc. All rights reserved worldwide. Cadence, 1st Silicon Success, Accelerating Mixed-Signal Design, Allegro, Assura, BuildGates, the CDNLive! logo, Concept, Conformal, Connections, Diva, Dracula, ElectronStorm, Encounter, EU CAD, Fire & Ice, First Encounter, HDL-ICE, Incisive, Invisible Specman, IP Gallery, InstallScape, Nano Encounter, NanoRoute, NC-Verilog, NeoCell, NeoCircuit, Neo Circuit-RF, NeoIP, OpenBook, OrCAD, OrCAD Capture, OrCAD Layout, Palladium, Pearl, PowerSuite, PSpice, SignalStorm, Silicon Design Chain, Silicon Ensemble, Silicon Express, SKILL, SoC Encounter, SourceLink, SPECCTRA, SPECCTRAQuest, Spectre, Specman, Specman Elite, SpeedBridge, Stars & Strikes, Verifault-XL, Verification Advisor, Verilog, Virtuoso, VoltageStorm, and Xtreme are either registered trademarks or trademarks of Cadence Design Systems, Inc. All others are the property of their respective holders.

